

Class-AB Speaker Amplifiers

1.1W to1.5W

Pb Rece ROHM Electronic Components Direct



Monaural Speaker Amplifier

BD7830NUV No.10077EAT03

Description

The BD7830NUV is a monaural speaker amplifier that operates at low voltage and was developed for portable navigation and mobile audio products. When in standby mode, its current consumption is 0 μ A, and since it switches quickly and quietly from standby to ON, it is especially well suited for applications where there is frequent switching between standby and ON.

Features

- 1) BTL monaural audio power amplifier
- 2) High power 2.25W 4Ω at Vcc=5V ,THD+N=10% High power 1.55W 8Ω at Vcc=5V ,THD+N=10% High power 0.77W 8Ω at Vcc=3.6V ,THD+N=10%
- 3) Wide operating supply voltage range: 2.4~5.5V
- 4) Low standby current: 0µA
- 5) Fast turn on/off time: 46msec
- 6) Built-in Fade-in/out function
- 7) Built-in anti-pop function
- 8) Built-in thermal shutdown function
- 9) Very small package (VSON008V2030)

Applications

Mobile phones, Mobile electronics applications

● Absolute Maximum Ratings(Ta=+25°C)

Parameter	Symbol	Ratings	Unit
Supply voltage	Vcc	6.0	V
Power dissipation	Pd	530 ^{*1}	mW
Storage temperature range	Tstg	-55~+150	°C
STBY input range	V _{STBY}	-0.1~Vcc+0.1	V

^{*1} ROHM standard one layer board (70mm×70mm×1.6mmt) mounted, deratings is done at 4.24mW/°C above Ta=+25°C.

Operating Range

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Parameter	Symbol	Ratings	Unit			
Temperature range	Topr	-40 ~ +85	°C			
Supply voltage	V _{CC}	+2.4~+5.5	V			

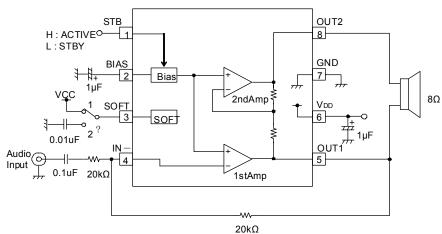
X This product is not designed for protection against radioactive rays.

• Electrical characteristics (Unless otherwise noted, Ta=+25°C, V_{CC}=+3.0V, f=1kHz, RL=8Ω)

Parameter	Symbol Limit			Unit	Monitor	Condition	
Farameter	Symbol	MIN.	TYP.	MAX.	Offic	pin	Condition
Supply current	Icc	_	3.2	6.8	mA	6	Active mode
Standby supply current	I _{STBY}	1	0	2	μΑ	6	Standby mode
Output power	Po	280	420	_	mW	5&8	BTL, THD+N=1% *1
Total harmonic distortion	THD+N		0.1	0.5	%	5&8	BTL, Po=150mW *1
Voltage gain1	A _{V1}	-1	0	+1	dB	5	Vin=-20dBV, 1stAmp
Voltage gain2	A _{V2}	-1	0	+1	dB	8	Vin=-20dBV, 2ndAmp
Power supply rejection ratio	PSRR	40	57	_	dB	5&8	BTL, Vripple=0.2Vpp *2
Mute attenuation	MUTE	60	80	_	dB	5&8	BTL, Vin=-20dBV
Output voltage	Vo	1.35	1.5	1.65	V	5&8	Vin=0V
Output offset voltage	ΔVo	-40	0	+40	mV	5&8	Δ Vo= Vo1-Vo2
STBY release voltage	V _{STBYH}	1.4	_	Vcc+0.1	V	1	Active mode
STBY hold voltage	V _{STBYL}	-0.1	_	0.4	V	1	Standby mode
STBY input current H	I _{STBYH}	20	30	40	μΑ	1	V _{STBY} =3V
STBY input current L	I _{STBYL}	-2	0	_	μΑ	1	V _{STBY} =0V

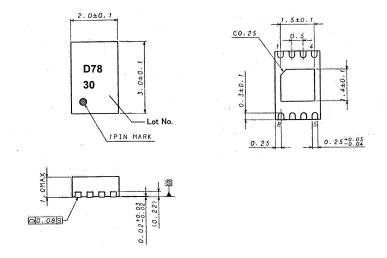
^{*1:}B.W.=400~30kHz, *2:DIN AUDIO, SE:Single End, BTL:The voltage between 5pin and 8pin

Application Circuit Example

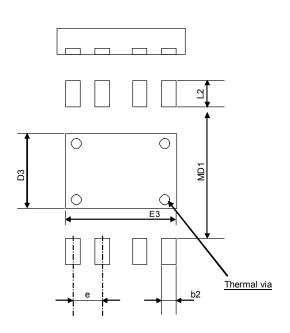


1 : Usually
2 : Enable to adjust fade in/out time by external capacitor

Outer dimension



● Reference land pattern (adapt as necessary to suit conditions during actual design.)

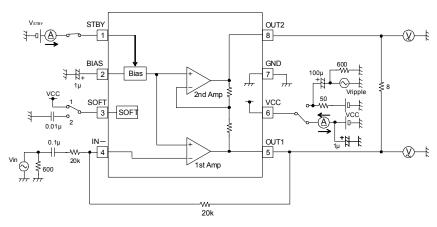


			UI	nit: mm	
PKG type	Lood nitch	Land			
	Lead pitch	Gap	Length	Width	
	е	MD1	L2	b2	
VSON008V2030	0.50	2.20	0.70	0.27	

	Centra	l pad	Thermal via		
PKG type	Length	Width	Pitch	Diameter	
	D3	E3	FILCII	Diameter	
VSON008V2030	1.20	1.60	_	φ 0.300	

 $\ensuremath{\mathbb{X}}$ This package is a non-lead type, so solderability of the lead ends and sides are not guaranteed.

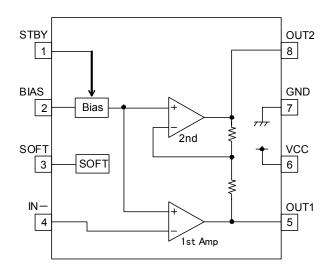
● Measurement Circuit Diagram



※3pin SOFT terminal

- Usually
 Enable to adjust fade in/out time by external capacitor

Block diagram



●Pin assignment

PIN No.	PIN Name			
1	STBY			
2	BIAS			
3	SOFT			
4	IN-			
5	OUT1			
6	VCC			
7	GND			
8	OUT2			

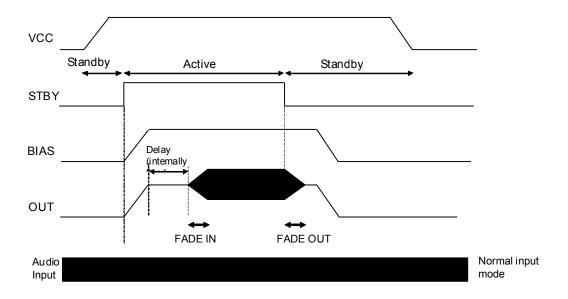
●Input/output equivalent circuit

PIN No.	PIN Name	PIN description	Equivalent circuit
1	STBY	Active/Standby Control pin STBY=H → Active STBY=L → Standby	STBY
2	BIAS	Bias capacitor Connection pin	BIAS
3	SOFT	Fade-in/out Adjustment pin	SOFT 1k
4	IN-	Input pin	1N- 1k
5 8	OUT1 OUT2	Output pin	OUT1 (OUT2) 5 \$60k
6	VCC	Power supply pin	VCC 6
7	GND	GND pin	7 GND

Notes) The above numerical values are typical values for the design, which are not guaranteed.

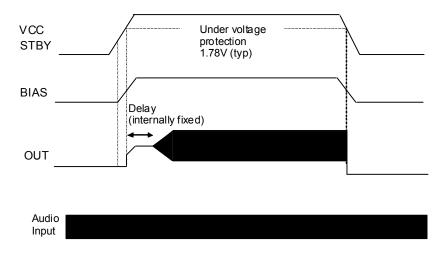
Description of operations

①ON/OFF operation by STBY pin



Once VCC = H, when STBY = L \rightarrow H then BIAS and output (OUT) are activated. Once BIAS has become stable (= 1/2 VCC), output (OUT) fades in (FADE IN). Once STBY = H \rightarrow L, output (OUT) starts to fade out (FADE OUT), and when fade-out ends, the BIAS falls.

2ON/OFF control by shorting of VCC and STBY pins

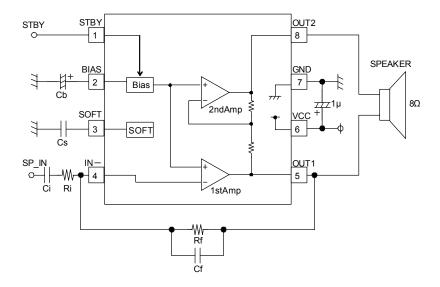


When VCC = STBY = L \rightarrow H, BIAS is activated. During low power mode (VCC < 1.78 V) protection is used to keep output (OUT) at low level, and FADE IN occurs when this protection is canceled. When VCC = STBY = H \rightarrow L, output (OUT) falls without FADE OUT.

Technical Note

External components and cautions points

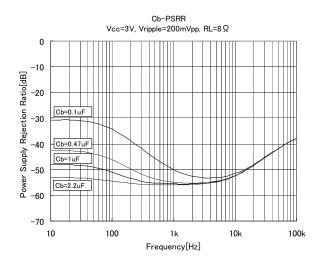
Setting of external components



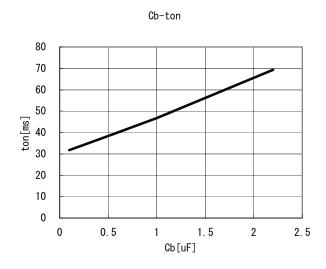
●Cb

This is a bypass capacitor, which is used for bias voltage stabilization. When a larger capacitor is used, the efficiency of voltage ripple rejection can be improved. When tuning, note with caution that Cb can affect the activation time.

Cb - Power Supply Ripple Rejection Ratio



Cb - Turn-on Time

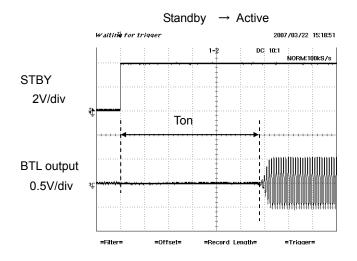


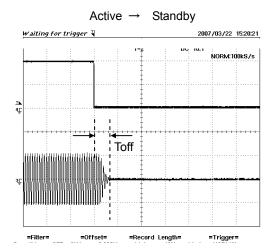
●Cs

This capacitor is for adjustment of the FADE IN/OUT times. The FADE IN/OUT functions soften the operation (IN and OUT) of BTL output when switching between standby and active modes.

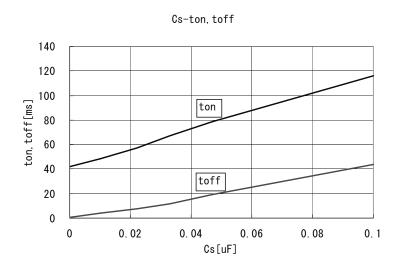
When a capacitor is connected to the SOFT pin (pin 3), the FADE IN/OUT functions are valid. When the capacitor rating is increased, the FADE IN/OUT effect is also increased, but note with caution when setting this that it also affects the activation time. If the FADE IN/OUT functions are not being used, connect the SOFT pin (pin 3) to VCC.

· Fade-in/out waveforms





Cs - Fade-in/out Time



●Ci

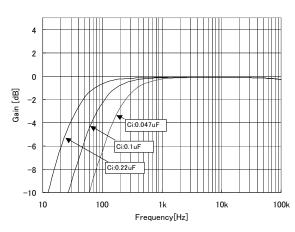
This is a DC cut-off input coupling capacitor for the amp input pin.

This includes an Ri and a high-pass filter. The cut-off frequency is calculated as follows.

$$f_{CL} = \frac{1}{2\pi \times Ri \times Ci}$$
 [Hz]

Ci - Low Frequency Characteristics

Ci-Frequency characteristic



Capacitors of a certain size are required for coupling without attenuation of low frequencies, but in most cases of speakers used in portable equipment, it is nearly impossible to reproduce signals in the 100 to 200 Hz range or below. Even when a larger capacitor is used instead, it may not improve system performance. Also, pop sounds can affect the capacitance (Ci) of the capacitor. A larger coupling capacitor requires a greater charge to reach the bias DC voltage (normally 1/2 VCC). Because this charge current is supplied from the output due to routing of feedback, pop sounds occur easily at startup. Consequently, pop sounds can be minimized by selecting the smallest capacitor that still has the required low-frequency response.

●Ri

This is inverting input resistance, which sets the closed loop gain in conjunction with Rf.

●R1

This is feedback resistance, which sets closed loop gain in conjunction with Rf. The amp gain is set using the following formula.

Gain =
$$20\log \left(\frac{Rf}{Ri}\right)$$
 [dB]

●Cf

This is a feedback capacitor, which is used to cut high frequencies.

This includes Rf and a low-pass filter. The cut-off frequency is calculated as follows.

$$f_{CL} = \frac{1}{2\pi \times Ri \times Ci}$$
 [Hz]

Selection of external components

1)Setting gain from desired output

Output Po is determined via the following formula, from which the required gain Av can also be obtained.

Po [W] = Vo² [Vrms] / RL [
$$\Omega$$
]
Vo = Av · Vin
Av $\geq \sqrt{\text{Po} \cdot \text{RL}}$ / Vin

2) Setting input resistance and feedback resistance from gain

Gain Av is determined via the following formula, from which input resistance Rin and feedback resistance Rf can be set.

Av = (Rf / Rin) • 2

Rin is set with the input side's drive capacity taken into account.

3 Setting input coupling capacitor from low-range cut-off frequency

Low-range cut-off frequency fc is determined via the following formula, from which input coupling capacitor Cin can be set.

fc [Hz] = 1 / (2
$$\pi$$
 · Rin · Cin)
Cin \ge 1 / (2 π · Rin · fc)

4 Setting bias capacitor and SOFT capacitor to minimize pops

It is recommended that the capacitance of the bias capacitor CB be set to at least 10 times that of the input coupling capacitor Cin, in order to soften the rise of the bias voltage while improving the Cin following ability.

Also, when a higher gain is used, the capacitance of the SOFT capacitor Cs can be raised to control pop sounds.

```
Av = 2 (6 dB at BTL) \rightarrow Cs · (80 / fc) \geq 0.01 \muF
Av = 4 (12 dB at BTL) \rightarrow Cs · (80 / fc) \geq 0.022 \muF
Av = 8 (18 dB at BTL) \rightarrow Cs · (80 / fc) \geq 0.033 \muF
Av = 20 (26 dB at BTL) \rightarrow Cs · (80 / fc) \geq 0.068 \muF
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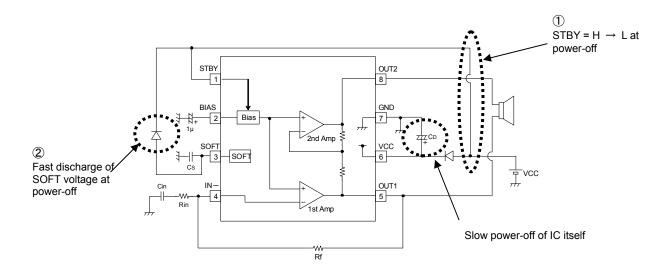
●Use when VCC = STBY short

Since this IC is designed on the assumption that it will be used to switch standby mode ON and OFF while the power supply remains ON, normally STBY should be switched from H to L and the SOFT voltage should be discharged before powering down. When used while VCC = STBY short, pop sounds may occur if the IC's power supply is reduced prior to discharging the SOFT voltage.

To prevent pop sounds, you must ① <u>set STBY = H \rightarrow L before setting VCC = H \rightarrow L, and ② <u>forcibly discharge the SOFT</u> voltage.</u>

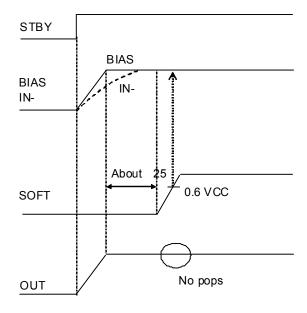
A sample circuit in which VCC = STBY short is used is shown below.

- Sample circuit configuration when VCC = STBY short

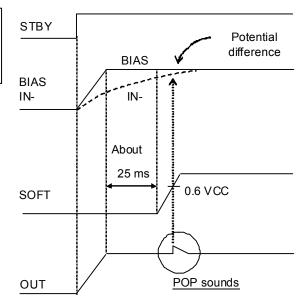


Mechanism of pop sounds

Cin is low Gain is low (Rf)



Cin is high Gain is high (Rf)

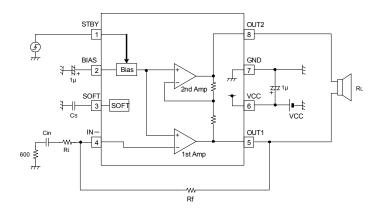


When SOFT voltage reaches 0.6 VCC, if there is a potential difference between BIAS and IN-, pop sounds will occur.

At startup, the input coupling Cin is charged from output OUT via the feedback resistance Rf, so when

Cin and Rf are high, charging takes longer and pop sounds can easily occur.

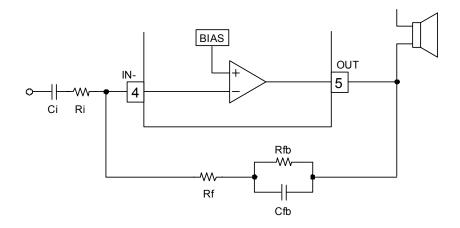
The rise of the SOFT voltage is changed by Cs, so pop sounds an be reduced by setting Cs high.

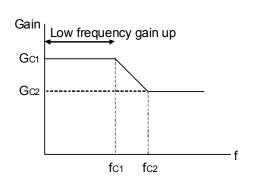


BD7830NUV Technical Note

Bass boost function

External components can be added to this chip to provide a bass boost function.





$$f_{C2} = \frac{1}{2\pi * Cfb * Rf}$$
 [Hz]

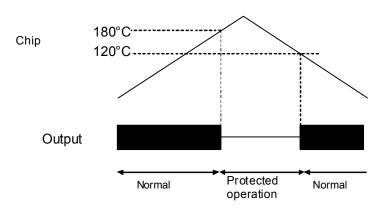
$$f_{C1} = \frac{1}{2\pi * Cfb * (Rf /\!/ Rfb)}$$
 [Hz]

$$G_{C1} = 20 \log \frac{Rf + Rfb}{Ri}$$
 [dB]

$$G_{C2} = 20 \log \frac{Rf}{Ri}$$
 (normal use) [dB]

●Thermal shutdown function

When the chip exceeds the Tjmax (150°C) temperature by reaching a temperature of 180°C or above, the protection function is activated. High impedance is for OUT1 and OUT2 during protected mode. Protection is canceled and normal operation is resumed when the chip's temperature falls to 120°C or below.



Protection start temperature: 180°C (typ) or more Protection cancels temperature: 120°C (typ) or less

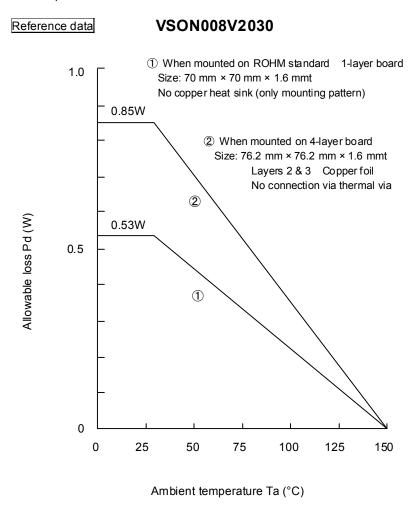
Thermal design of chip

The characteristics of the IC vary greatly depending on the use temperature, and when the maximum allowable junction temperature is exceeded, components may deteriorate or become damaged. Thermal considerations are needed for this chip from two standpoints: preventing instantaneous damage and improving long-term reliability. Note the following points with caution.

The absolute maximum ratings for each chip include the maximum junction temperature (T_{jMAX}) and operating temperature rate (T_{opr}) , and these values should be referred to when using the Pd-Ta characteristics (thermal dissipation curve). Since the IC itself is designed with full consideration of thermal balance, there are no problems in terms of circuit operations, but even when a more-than-adequate thermal design is implemented in order to get full use of the IC's performance features, some moderation is often required for the sake of practical usage.

If there is an excessive input signal due to insufficient thermal dissipation, a TSD (thermal shutdown) operation may occur.

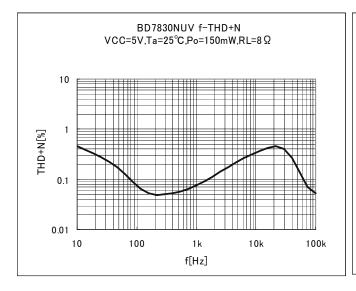
Thermal Dissipation Curve

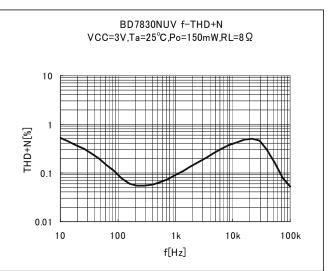


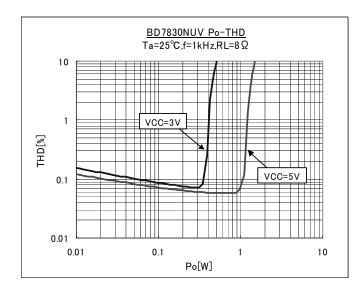
(Note) These are measured values. They are not guaranteed.

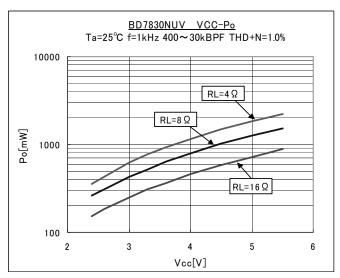
The allowable loss value varies depending on the type of board used for mounting. When this chip is mounted on a multi-layer board that is designed for thermal dissipation, the allowable loss becomes greater than shown in the above figure.

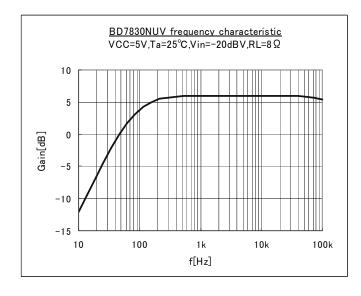
● Typical Characteristics (1)

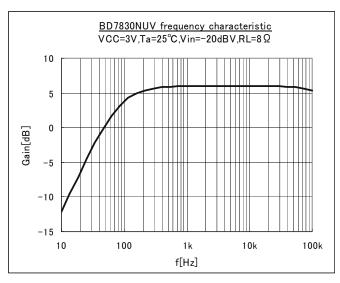




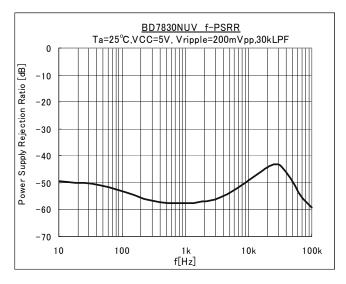


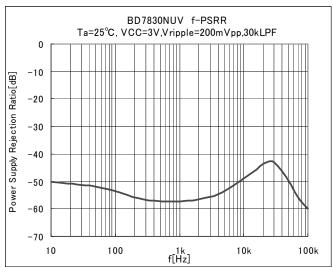


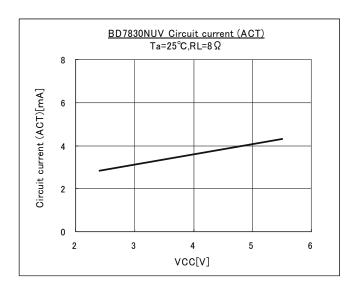


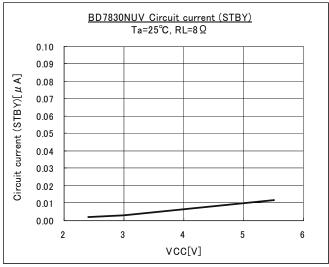


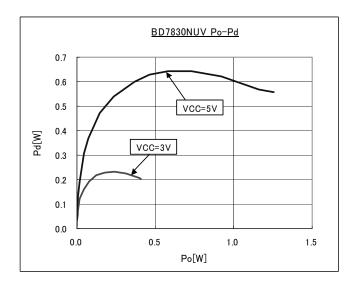
● Typical Characteristics (2)

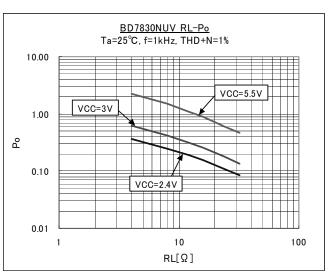












BD7830NUV Technical Note

Notes for use

- 1) The above numerical values and data are typical values for the design, which are not guaranteed.
- 2) The application circuit examples can be reliably recommended, but their characteristics should be checked carefully before use. When using external component constants that have been modified, determine an ample margin that takes into consideration variation among the external components and Rohm's LSI IC chips, including variation in static characteristics and transient characteristics.

3) Absolute maximum ratings

This IC may be damaged if the absolute maximum ratings for the applied voltage, temperature range, or other parameters are exceeded. Therefore, avoid using a voltage or temperature that exceeds the absolute maximum ratings. If it is possible that absolute maximum ratings will be exceeded, use fuses or other physical safety measures and determine ways to avoid exceeding the IC's absolute maximum ratings. The above numerical values and data are typical values for the design, which are not guaranteed.

4) GND pin's potential

Try to set the minimum voltage for GND pin's potential, regardless of the operation mode. Check that the voltage of each pin does not go below GND pin's voltage, including transient phenomena.

5) Shorting between pins and mounting errors

When mounting the IC chip on a board, be very careful to set the chip's orientation and position precisely. When the power is turned on, the IC may be damaged if it is not mounted correctly. The IC may also be damaged if a short occurs (due to a foreign object, etc.) between two pins, between a pin and the power supply, or between a pin and the GND.

6) Shorting output pin

When output pin (5,8pin) is shorted to VCC or GND, the IC may be damaged by over current, so be careful in operation.

7) Thermal design

Ensure sufficient margins to the thermal design by taking in to account the allowable power dissipation during actual use modes, because this IC is power amp.

When excessive signal inputs which the heat dissipation is insufficient condition, it is possible that TSD (thermal shutdown circuit) is active.

TSD is protection of the heat by excessive signal inputs, it is not protection of the shorting output to VCC or GND.

8) Shorted pins and mounting errors

When the output pins (pins 5 and 8) are connected to VCC and GND, the thermal shutdown function repeatedly switches between shutdown (OFF) and cancel (ON). Note with caution that chip damage may occur if these connections remain for a long time.

9) Operating range

The rated operating power supply voltage range(VCC= $\pm 2.4 \sim \pm 5.5$ V) and the rated operation temperature range (Ta= $\pm 40 \sim \pm 85$ °C) are the range by which basic circuit functions is operated.

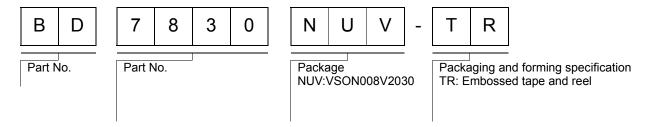
It is not guaranteed a specification and a rated output power about all operating power supply voltage range or operation temperature range.

10) Operation in strong magnetic fields

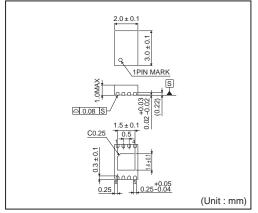
Note with caution that operation faults may occur when this IC operates in a strong magnetic field.

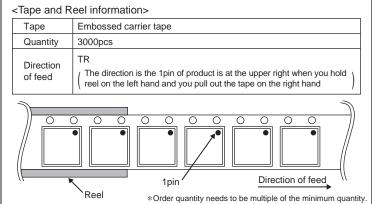
Technical Note

Ordering part number



VSON008V2030





Notes

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